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ELECTRONIC COMPONENTS GROUP
SHARP CORPORATION

PAGE

8 Pages

SPECIFICATION

REPRESENTATIVE DIVISION
OPTO-ELECTRONIC DEVICES DIV.

M. Abe *Sep. 01, 1995*

DEVICE SPECIFICATION FOR
GaP Yellow-green
Chip LED Device

MODEL No. LT1E62A

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2. Please obey the absolute maximum ratings and notes etc. in these specification sheets, and the notice mentioned below for actual use of this device. SHARP takes no responsibility for any damage caused by improper use of the device deviated from the absolute maximum ratings and notes etc. in these specification sheets, and the notice mentioned below for actual use of this device.

(Notice)

(1) This device is designed for use in the following applications;

- . OA equipment . Audio visual equipment . Home appliance
 - . Telecommunication equipment (Terminal) . Measuring equipment
 - [. Tooling machine . Computer, etc.
- among those applications, if there is applicable to the item(2), and(3).
Please obey the corresponded not ice.

(2) The appropriate measures, such as fail-safe design and redundant design considering safety design of overall system and equipment, should be taken to ensure the reliability and safety in the function and precision when this device is used for equipment, such as;

- . Transportation control and safety equipment (aircraft, train, automobile etc.)
- . Traffic signal . Gas leakage sensor breaker ● Fire box and burglar alarm box
- [. Other safety equipment, etc.

(3) Please do not use for the uses mentioned below which require extremely high reliability and safety in function and precision

- . Space equipment . Telecommunication equipment (Trunk)
- [. Nuclear power control equipment . Medical equipment etc.]

(4) Contact and consult with a Sharp representative if there are any questions when intending to use this device for any applications listed above or applicable to the listed above.

3. Contact and consult with a Sharp representative, in advance, if there any questions about this device.

CUSTOMER'S APPROVAL

DATE

BY

DATE
PRESENTED
BY

Sep. 1, 1995

M. Abe

M. Abe
Department General Manager of
Engineering Dept. , III
Opto-Electronic Devices Div.
ELECOM Group
SHARP CORPORATION

SHARPLT1E62A

This **data** sheet is to introduce the light emitting diode device
Model No. LTI E62A, delivered to

1. Structure and characteristics

Structure : **GaP** yellow-green chip LED device

Outline dimensions **and** pin connections : See page 2

Taping specification : See page 3 4 5 6

Packing specification : See page 7

Soldering method : See page 8

Z. Absolute **maximum** ratings

(Ta = 25°C)

Parameter	Symbol	Value	Unit
Power dissipation	P	8.4	mW
Continuous forward current	I _F	30	mA
Peak forward current (Note 1)	I _{FM}	50	mA
Derating factor	DC	0.40	mA/°C
	Pulse	0.67	mA/°C
Reverse voltage	V _R	5	V
Operating temperature	T _{opr}	-30 ~ +85	°C
Storage temperature	T _{stg}	-40 ~ +100	°C

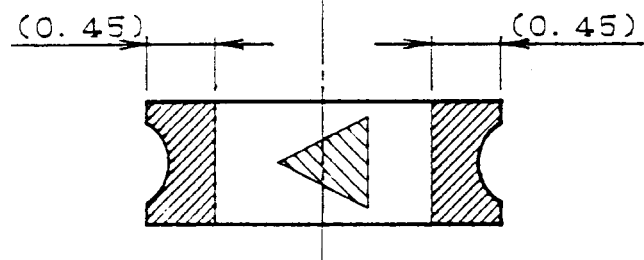
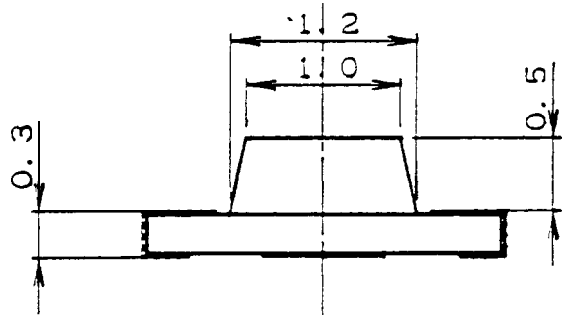
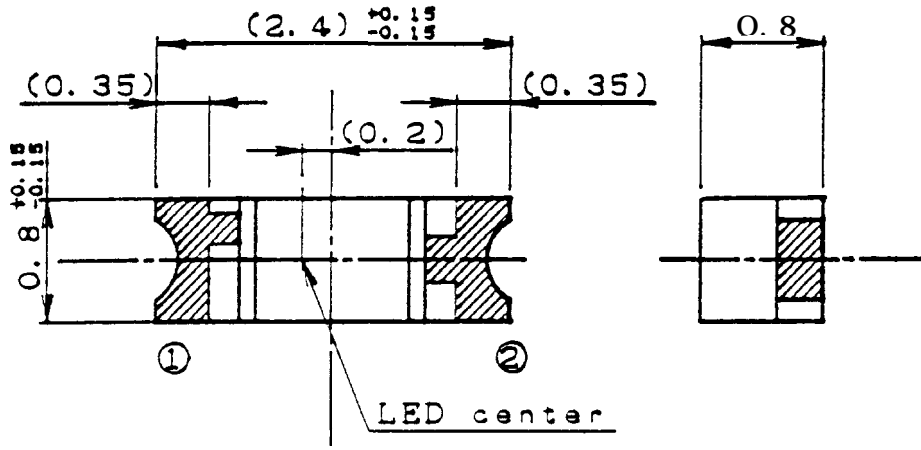
(Note 1) Duty ratio = 1/10, Pulse width = 0.1 μs



3. Electro optical characteristics

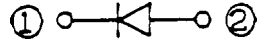
(Ta = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward voltage	V _F	I _F = 20 mA	-	2.1	2.8	v
Luminous intensity (Note 2)	I _v		9.4	19	-	mcd
Peak emission wavelength	λ _p		-	565	-	nm
Spectrum radiation bandwidth	Δλ		-	30	-	nm
Reverse current	I _R	V _R = 4 V	-	-	10	μA
Terminal capacitance	C _t	V = 0V, f = 1MHz	-	35	-	pF

(Note 2) Tolerance: ±15%



1. Plated area 
 Resist area 

2. Pin Connection
 Q Cathode
 Q Anode


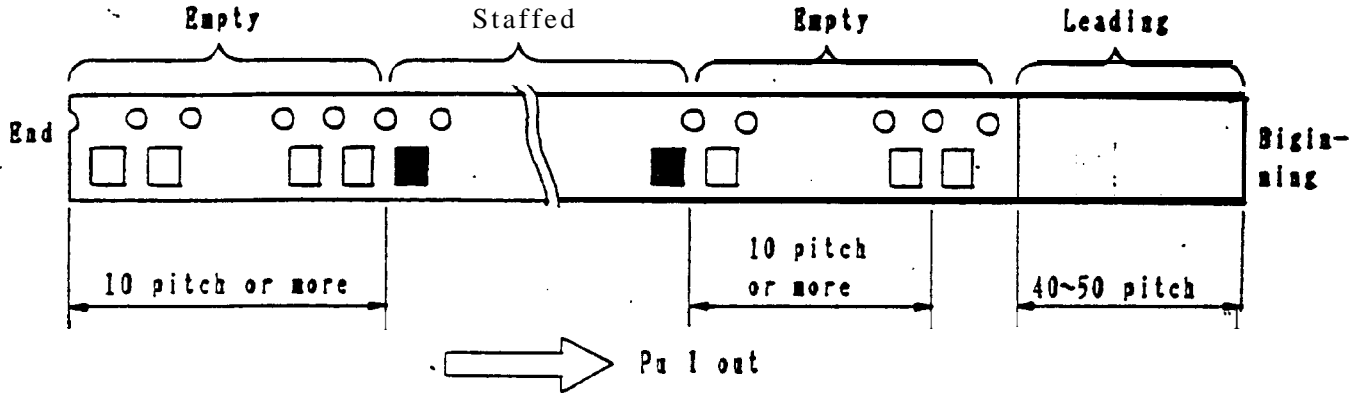
3. Unspecified tel. to be ±0.1

適用機種 APPLICABLE MODEL		尺度 SCALE		単位 UNIT				
LT1E62A		20/1		mm		改訂日 DATE	改訂記事 REVISE	担当 CHNG
反厚 THICKNESS	員数 PIECES	材質 MATERIAL	仕上 FINISH			名称 NAME	Outline dimensions and terminal connections	
			Auめっき					
日付 DATE	1995. 5. 29	シャープ株式会社電子部品事業本部				コード CODE		
設計 DESIGN	製図 DRAW	検図 CHECK	検図 CHECK	承認 APPROVE	オプトデバイス(事)第3技術部			
					OPTO-ELECTRONIC DEVICES DIV			
					ELECOM GROUP			
					SHARP CORPORATION			
						図番 DRAWING No.	50604026M	



Taping Specification

1. This data sheet is to introduce the taping specification of LRD device, model No. LT1E62A
2. Taping specification
 - 2.1 Taping specification



2.2 Shipment table

SHIPMENT TABLE	
PART No.	← Model number
QUANTITY	← Quantity of products
LOT No.	← Lot number* : <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/>
SHARP	
MADE IN JAPAN	

← Model number
 ← Quantity of products
 ← Lot number* :
 ① ② ③ ④ ⑤

*:Lot indication

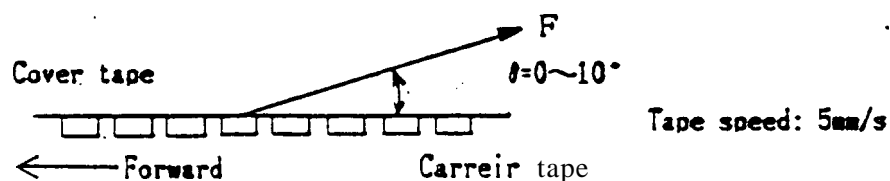
- ① Production plant code(to be indicated alphabetically)
- ② Production lot(single or double figures)
- ③ Year of production(the last two figures of the year)
- ④ Month of production
(to be indicated alphabetically with January corresponding to A)
- ⑤ Date of production(01~31)

SHARP**2.3 Related matters****2.3.1. Packing,**

There should not be missing above continuous **three products.**

2.3.2. Tape strength

1) **Cover tape strength against peeling: $F = 0.1 \sim 0.8N$ ($\theta = 10^\circ$ or less)**

**2) Tape strength against bending**

The radius of bending circle should be **30mm or more.**

If it is less than **30mm, the cover tape may peel.**

2.3.3. Taking out of products

- 1) Products should be easily taken out.
- 2) Products should **not** be attached to the cover tape at peeling.

2.3.4. Jointing of tape

There should not be joint of cover tape or carrier tape.

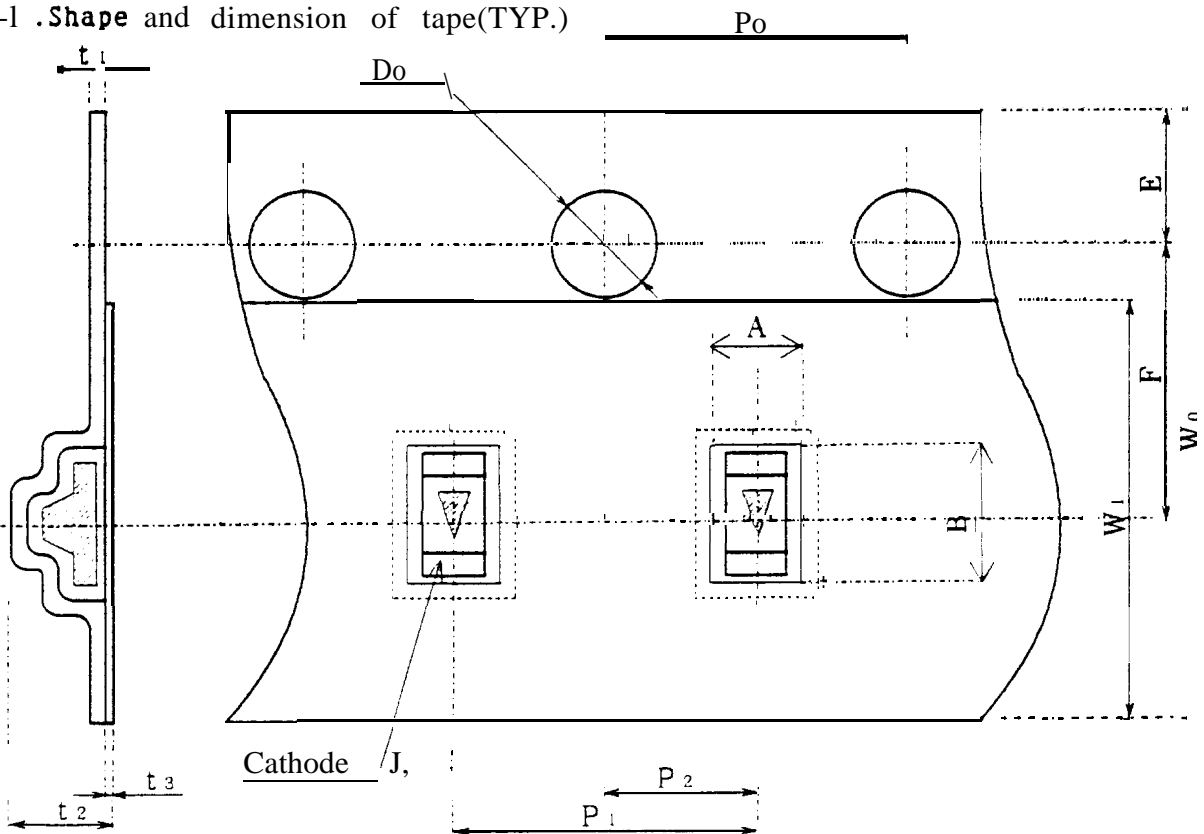
3. Quantity per reel

Average: **4,000** Pcs. per reel "

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4-1. Taping

4-1-1 .Shape and dimension of tape(TYP.)

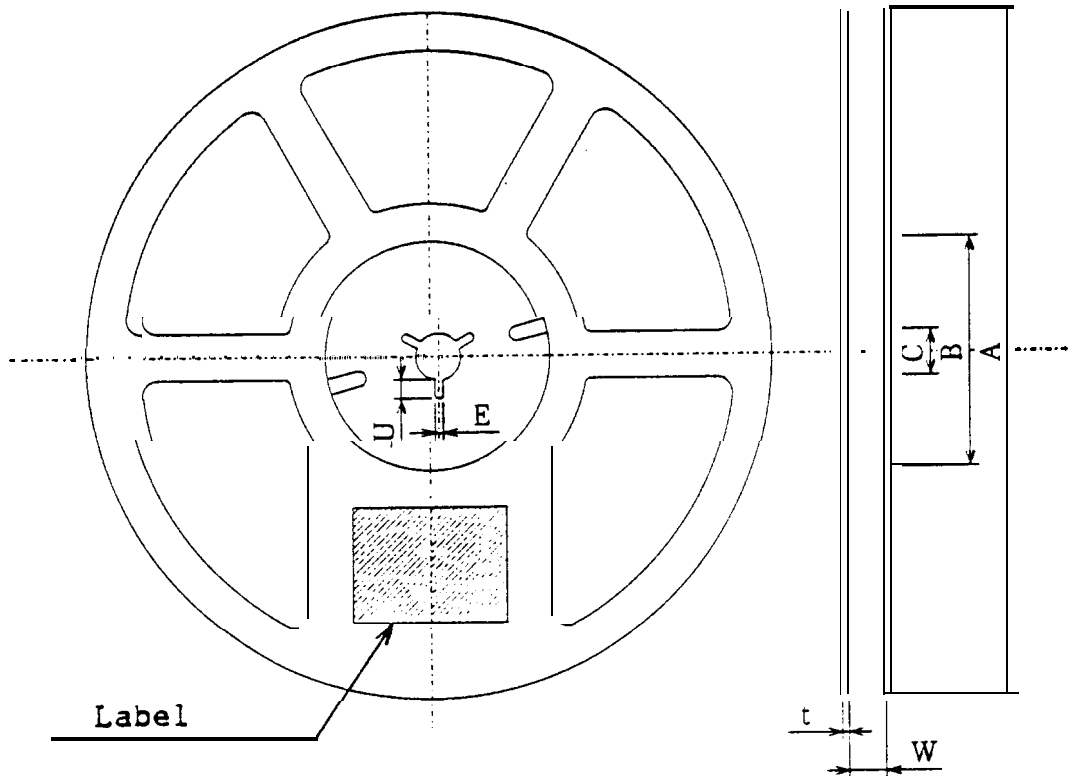


Parameter	Symbol	Dimension	Remarks	
Concave square hole for part insertion	Vertical	A	1.2 mm	Dimension excludes corner R at inside bottom
	Horizontal	B	2.1 mm	
	Pitch	P ₁	4.0mm	
Round sprocket hole	Diameter	D ₀	1.5mm	
	Pitch	P ₀	4.0mm	Accumulated error ±0.5mm/10 pitch
	Position	E	1.75mm	Distance between tape edge and hole center
Center to center dimension	Vert.dire	P ₂	2.0mm	Center line of the concave square hole and round sprocket hole
	Hori.dire	F	3.5mm	
Cover tape	Width	W ₁	5.5mm	
	Thickness	t ₃	0.1mm	
Carrier tape	Width	W ₀	8.0mm	
	Thickness	t ₁	0.2mm	
Thickness of the entire unit	t ₂	1.3 mm	With cover tape and carrier tape combined	

※ Material: Carrier tape. ..PET, Cover tape. ..Polyester

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4-1-2. Shape and dimension of reel (TYP.)

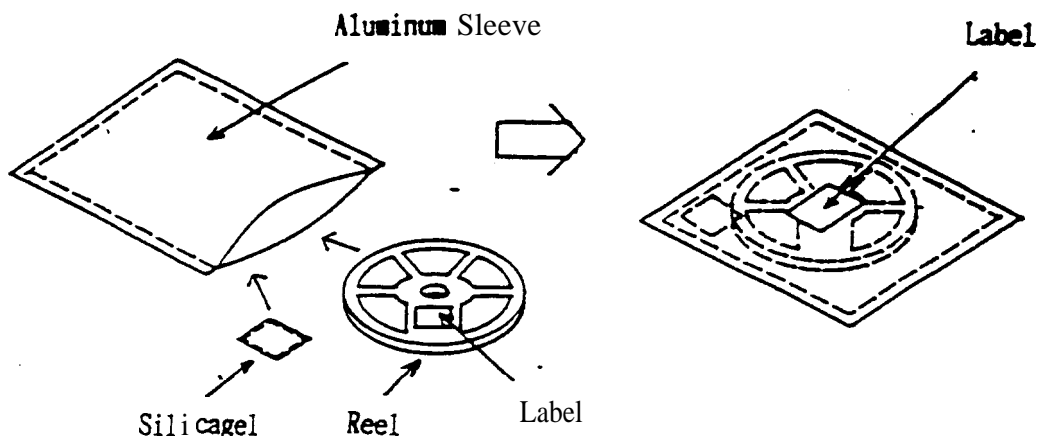


Parameter		Symbol	Dimension	Remarks
Flange	Diameter	A	φ 178mm	
	Thickness	t	1.5mm	
	Inner space direction	W	10mm	Dimension of shaft core
Hub	External diameter	B	φ 60mm	
	Spindle hole diameter	C	φ 13mm	
	Key slit..	Width	E	2.0mm
Depth		U	4.5mm	
Notation for part name etc.		Labeling on one side of flange. (Part name, quantity, lot No.)		

* Material: Reel...Polystyrene

SHARP**Packing Specification**

In order to avoid the absorption of humidity in transport and storage, the devices are packed in aluminum sleeve.

**1. Storage Conditions**

The storage should be done under following conditions:

Temperature 5 to 30°C

Humidity less than 60%RH

2. Treatment after Opening

1) Please make a soldering within 2 days after opening under following conditions:-

Temperature 5 to 30°C

Humidity less than 60%RH

2) In case the devices are not used for a long time after opening, the storage in dry box is recommendable. Or it is better to repack the devices with a desiccative by the sealer and put them in the same storage conditions as 6-1. Then they should be used within 2 weeks.

3) Please make a soldering after a following baking treatment if unused term should be over the conditions of 2).

Recommendable Conditions:

① in taping

Temperature 60°C Time 90 to 100 Hours

② in individual (on PWB or metallic tray)

Temperature 110°C Time 3 to 4 Hours

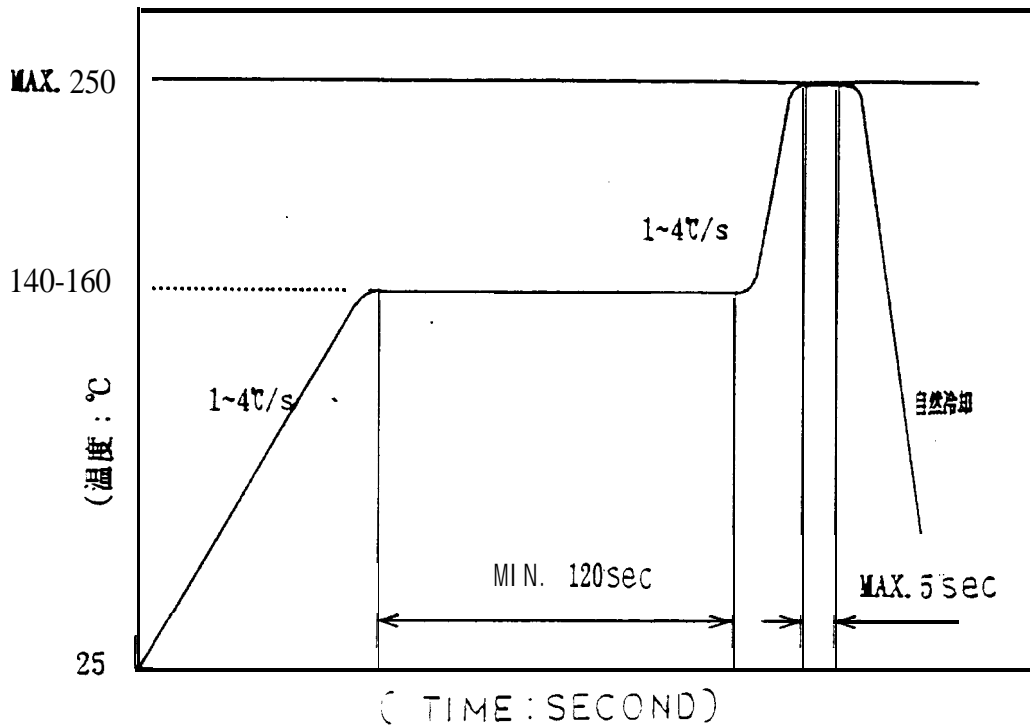
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Mounting precautions

1. Soldering

1-1 Reflow soldering

To be done-under the following condition.

Recommendable Thermal Model

1-2 Reflow soldering precautions

Second time soldering should be done within 8 hours after the first one is finished.
 (Storage condition: at 30°C, RH < 60%)

2. Soldering iron method

At 300°C within seconds

When using a soldering iron, care must be taken not to damage the package
 (Pay attention not to allow any undue stress or heat on package.)